Express Mail No. EV904401128US

OIPE	WARES
AUG 24	5000
BATENTE TOM	

Attorney Docket No. 108298737US Disclosure No. 03-06775.00/US

AMENDMENT TRANSMITTAL LETTER					Docket No. 108298737US			
Application No. 10/687,096-Conf. #7233		Filing Date October 15, 2003		Examiner S. W. Crane	÷	Art Unit 2811		
pplicant(s): Jam								
vention: METHODS FOR WAFER-LEVEL PACKAGING OF MICROELECTRONIC DEVICES AND MICROELECTRONIC DEVICES FORMED BY SUCH METHODS								
TO THE COMMISSIONER FOR PATENTS								
Transmitted herewith is an amendment in the above-identified application.								
The fee has been calculated and is transmitted as shown below.  CLAIMS AS AMENDED								
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate				
Total Claims	38	- 67 =		x				
Independent Claims	3	- 10 =		×				
Multiple Dependent Claims (check if applicable)								
Other fee (please specify):								
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00			
x Large Entity Small Entity								
x No additional fee is required for this amendment.								
Please charge Deposit Account No in the amount of \$  A duplicate copy of this sheet is enclosed.								
A check in the	ne amount of \$		to cover	the filing fee is end	closed.			
Payment by	credit card. F	orm PTO-2038	3 is attached.					
The Director is hereby authorized to charge and credit Deposit Account No. 50-0665 as described below. A duplicate copy of this sheet is enclosed.								
L	ny overpayme							
x Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.								
$\mathcal{M}$	//			Dated:	August	24, 2006		
Aaron J./Polep Attorney/Agent	na Reg. No.: 54,	675						
PERKINS COII P.O. Box 1247 Seattle, Washi (206) 359-8000	ngton 98111-1	247						

Attorney Docket No. 108298737US Disclosure No. 03-0675.00/US

AUG 2 4 2006 W

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: JAMES L. VOELZ

EXAMINER:

SARA W. CRANE

APPLICATION NO.:

10/687,096

ART UNIT:

2811

FILED:

OCTOBER 15, 2003

CONF. NO:

7233

For:

**METHODS FOR WAFER-LEVEL** 

PACKAGING OF MICROELECTRONIC DEVICES AND MICROELECTRONIC DEVICES FORMED BY SUCH METHODS

## Amendment Under 37 C.F.R. § 1.111

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

The present communication responds to the Office Action dated June 2, 2006 in the above-identified application. Please amend the application as follows:

Amendments to the Claims are reflected in the listing of claims beginning on page 2. Remarks begin on page 8 of this paper.